

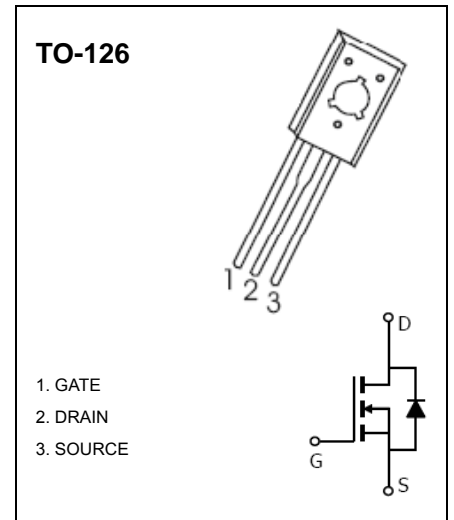


## TO-126 Plastic-Encapsulate MOSFETS

### CJI02N60 N-Channel Power MOSFET

#### General Description

The high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power suppliers, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.



#### FEATURES

- Robust High Voltage Termination
- Avalanche Energy Specified
- Diode is Characterized for Use in Bridge Circuits

#### Maximum ratings ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	2	A
Pulsed Drain Current	$I_{DM}$	8	
Power Dissipation	$P_D$	1.25	W
Single Pulsed Avalanche Energy*	$E_{AS}$	128	mJ
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	100	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-50 ~ +150	
Maximum lead temperature for soldering purposes , 1/8" from case for 5 seconds	$T_L$	260	$^{\circ}\text{C}$

\* $E_{AS}$  condition:  $T_J=25^{\circ}\text{C}$ ,  $V_{DD}=50\text{V}$ ,  $L=64\text{mH}$ ,  $I_{AS}=2\text{A}$ ,  $R_G=25\Omega$

**Electrical characteristics (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	600			V
Drain-source diode forward voltage(note2)	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 2A			1.6	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V			25	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ± 20V			± 100	nA
<b>On characteristics (note2)</b>						
Gate-threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.0		4.0	V
Static drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1A			4.4	Ω
Forward Transconductance (note1)	g <sub>FS</sub>	V <sub>DS</sub> = 50V, I <sub>D</sub> = 1A	1			S
<b>Dynamic characteristics (note 3)</b>						
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		435		pF
Output capacitance	C <sub>OSS</sub>			56		
Reverse transfer capacitance	C <sub>RSS</sub>			9.2		
<b>Switching characteristics (note 3)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 300V, V <sub>GS</sub> = 10V, R <sub>G</sub> = 18Ω, I <sub>D</sub> = 2A		12		ns
Turn-on rise time	t <sub>r</sub>			21		
Turn-off delay time	t <sub>d(off)</sub>			30		
Turn-off fall time	t <sub>f</sub>			24		

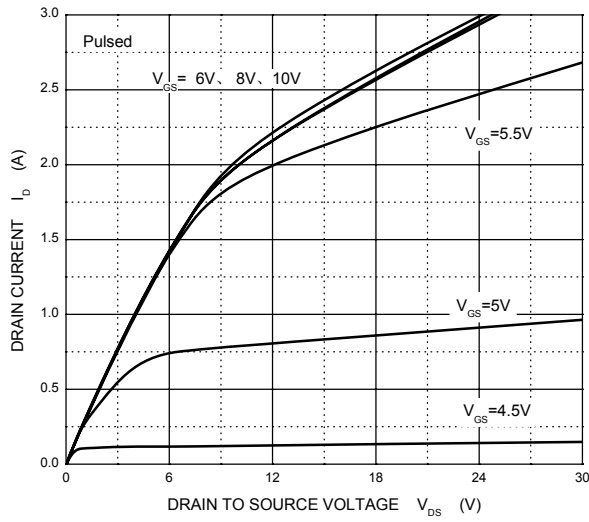
**Notes :**

1. L=16mH, I<sub>L</sub>=5A, V<sub>DD</sub>=50V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
2. Pulse Test : Pulse width ≤ 300μs, duty cycle ≤ 2%.
3. These parameters have no way to verify.

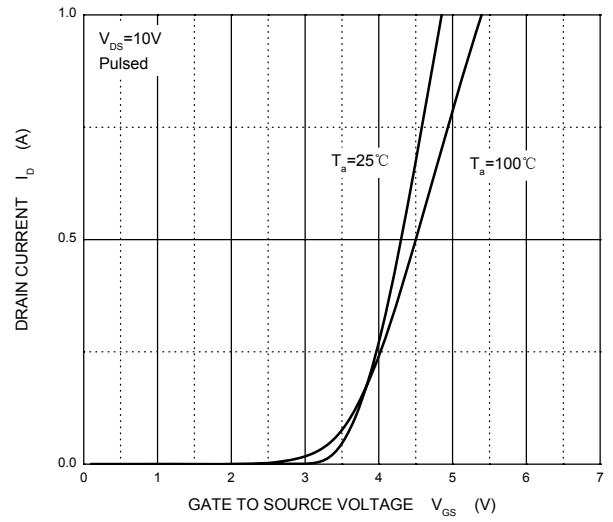
# Typical Characteristics

# CJI02N60

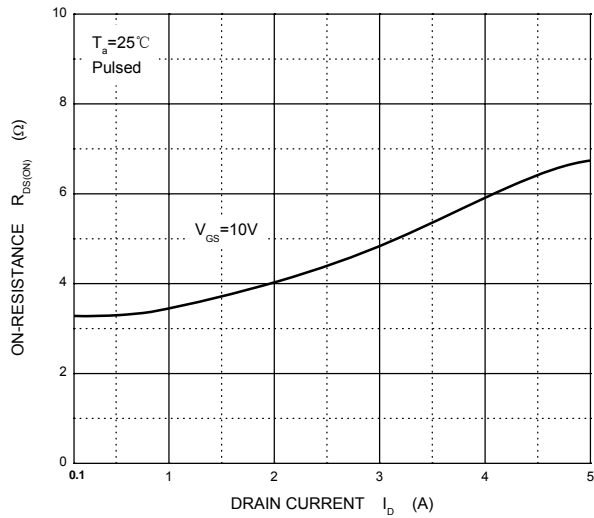
Output Characteristics



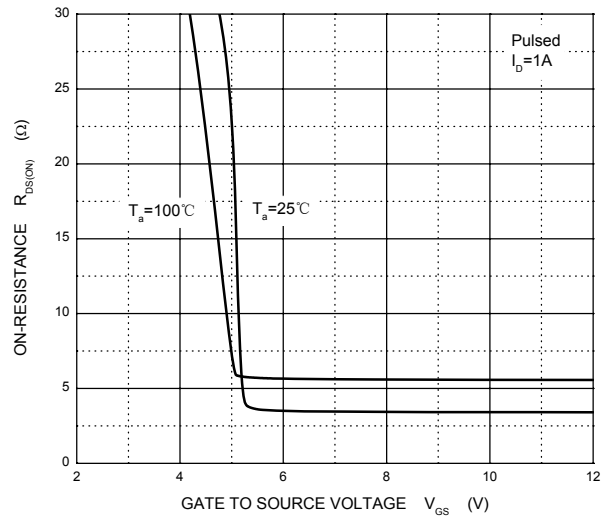
Transfer Characteristics



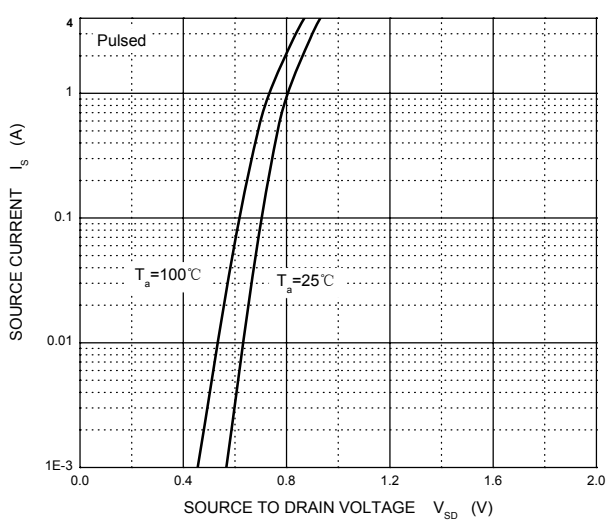
$R_{DS(ON)}$  —  $I_D$



$R_{DS(ON)}$  —  $V_{GS}$



$I_S$  —  $V_{SD}$



Threshold Voltage

